

(5.08 mm) .200"

HPF SERIES

POWER SOCKETS

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HPF

Insulator Material:

Black LCP

Contact Material:

BeCu

Plating:

Sn over

50 μ " (1.27 μ m) Ni

Insertion Depth:

(3.68 mm) .145" to (8.26 mm)

.325" (.368" (9.35 mm) plus

board thickness minimum for

bottom entry)

Wiping Distance:

(0.38 mm) .015"

Standard Creepage:

(2.82 mm) .111" (without -LC)

(1.38 mm) .054" (with -LC)

Standard Clearance:

(2.5 mm) .098" (without -LC)

(1.05 mm) .041" (with -LC)

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.15 mm) .006" max (02-10)

(0.20 mm) .008" max (11-20)

RoHS Compliant:

Yes

Mates with:

HPM, HPW

**POWER
EYE
CONTACT**

HPF/HPM	
PINS	CURRENT RATING (PER CONTACT)
1	16.6 A
2	14.4 A
3	13.2 A
4	12.7 A
ALL	8.9 A

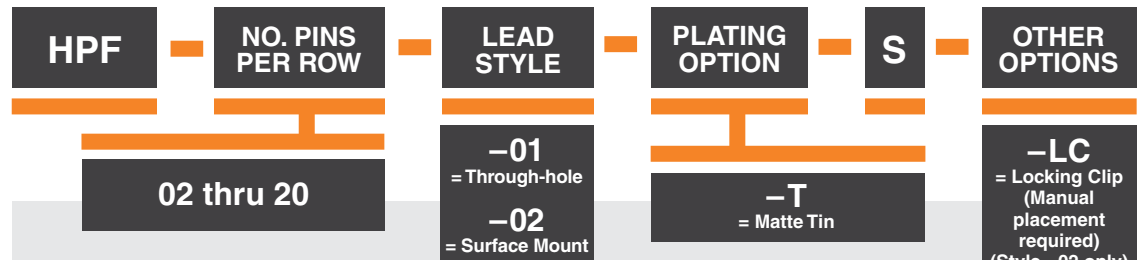
Surface Mount
or
Through-hole

RUGGEDIZED
BY SAMTEC

- Three-finger Power Eye contact
- Locking clip option

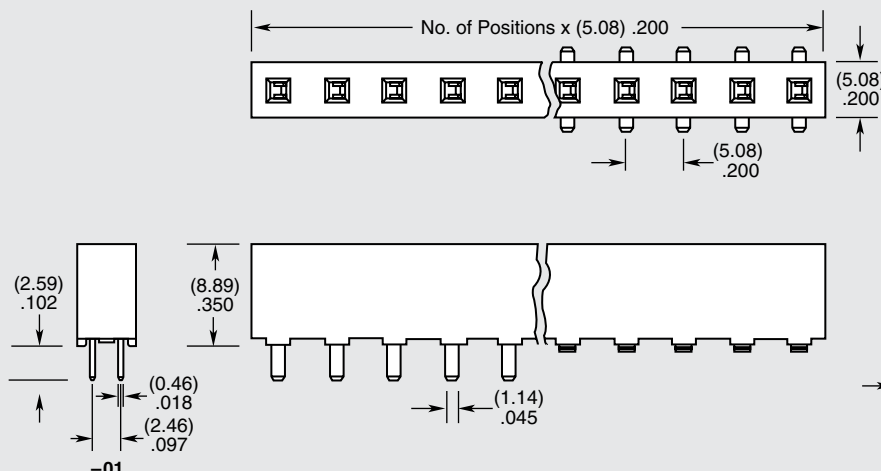
RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Increased creepage and clearance with the removal of contacts
- Contact Samtec.



Note: Some lengths, styles and options are non-standard, non-returnable.